Material Composition Specification

SMDIP Case

Pb (lead)-free plating**

Device average mass . . . . 300 mg

Fluctuation margin . . . . +/-10%

Component	Material	Material (%wt)	Material (mg)	Substance	CAS No.	Substance (%wt)	Substance (mg)	Substance (ppm)
active device	doped Si	1.2%	3.6	Si	7440-21-3	1.2%	3.6	12,000
leadframe	copper	21.21%	63.63	Cu	7440-50-8	21.2%	63.63	212,000
die attach	high temperature solder paste	0.865%	2.6	Pb	7439-92-1	0.8%	2.4	8,000
				Sn	7440-31-5	0.043%	0.13	430
				Ag	7440-22-4	0.022%	0.065	220
encapsulation*	EMC	74.39%	223.18	silica	7631-86-9	50.586%	151.759	505,860
				epoxy resin	Proprietary	22.317%	66.953	223,170
				Sb_2O_3	1309-64-4	0.744%	2.232	7,440
				TBBA	79-94-7	0.744 %	2.232	7,440
	EMC GREEN	74.39 %	223.18	silica	7631-86-9	51.62%	154.856	516,185
				epoxy resin	Proprietary	22.77%	68.32	227,725
plating**	tin lead process	2.333%	7.0	Sn	7440-31-5	1.866%	5.6	18,660
				Pb	7439-92-1	0.467%	1.4	4,670
	100% tin process	2.333%	7.0	Sn	7440-31-5	0.77%	0.708	7,700

*EMC GREEN molding compound is Halogen-Free.
**Specify Lead-Free when ordering 100% tin (Pb-free) plating.

Disclaimer
The information provided in this Material Composition data sheet is, to our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.